

CLAIM AMENDMENTS:

Please amend Claim 55 as follows:

1.-22. (Cancelled)

23. (Previously Presented) The imaging apparatus according to Claim 55, wherein the wavelength converting member comprises a fluorescent member.

24. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises an insulating base and a conductive layer provided thereon.

25. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises a metal.

26. (Previously Presented) The imaging apparatus according to Claim 25, wherein the metal comprises aluminum.

27. (Cancelled)

28. (Previously Presented) The imaging apparatus according to Claim 55, wherein an area of the conductive member overlaps said photoelectric conversion elements.

29. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member is sealed.

30. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member extends over the outer edges of the and an edge portion of said conductive member is sealed so as to cover the outer edges of the plurality of substrates.

31. (Previously Presented) The imaging apparatus according to Claim 30, wherein a space is formed between the outer edges of said plurality of substrates and the conductive member.

32. (Previously Presented) The imaging apparatus according to Claim 30, wherein said outer edges of said plurality of substrates and the conductive member are in close contact with each other.

33. (Previously Presented) The imaging apparatus according to Claim 31, wherein a resin is provided in the space.

34. (Previously Presented) The imaging apparatus according to Claim 55, wherein a resin is provided which covers said plurality of substrates and all the end faces of the conductive member.

35. (Previously Presented) The imaging apparatus according to Claim 55, wherein the plurality of photoelectric conversion elements are arranged in a matrix.

36. (Previously Presented) The imaging apparatus according to Claim 26, wherein the metal has a thickness of 100 μm or less.

37. - 54. (Cancelled)

55. (Currently Amended) An imaging apparatus comprising, ~~the~~
~~photoelectric conversion device;~~

a photoelectric conversion device having a ~~conductive member~~, a
plurality of substrates each having a plurality of photoelectric conversion elements, the
plurality of substrates being arranged adjacent each other in a plane, and a wavelength
converting member ~~disposed between the photoelectric conversion elements and the a~~
~~conductive member, stacked and~~ arranged on the photoelectric conversion elements over the
plurality of substrates ~~wherein said conductive member is grounded;~~

a control circuit for driving the device; ~~and~~

a housing for said photoelectric device and said control circuit, ~~wherein~~
~~said; and~~

a grounded conductive member ~~is~~ disposed between said housing and
said wavelength converting member.